

PATENT
Customer No. 22,852
Attorney Docket No. 4329.2197-01

TO/10/90
USPTO
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Divisional Application of:) Parent Application:
Masaki ADACHI et al.) Serial No. 09/451,755
Serial No.: Not Yet Assigned) Filed: December 1, 1999
Filed: June 1, 2001) Group Art Unit: 2811
For: COMPOSITION FOR SEALING A) Examiner: N. Parekh
SEMICONDUCTOR DEVICE,
SEMICONDUCTOR DEVICE AND
METHOD OF MANUFACTURING THE
SAME)

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

PRELIMINARY AMENDMENT

Prior to the examination of the above application, please amend this application as follows:

IN THE CLAIMS:

Please cancel claim 1 without prejudice to, or disclaimer of, the subject matter thereof and add new claims 21-32 as follows.

--21. (New) A thermoplastic material suitable for sealing a part of a conducting material and a semiconductor element electrically coupled with the conducting material,

prop 9 polyphenylene sulfide